

| External_Type  | Material_Group   | Substances                                    | CAS_Number | Mass      | Mass_Percentage_in_Leaf | Massmg   |
|----------------|------------------|-----------------------------------------------|------------|-----------|-------------------------|----------|
| Die            | Doped silicon    | Silicon (Si)                                  | 7440-21-3  | 0.26824   | 100.0                   | 0.61     |
| Subtotal       |                  |                                               |            | 0.26824   | 100                     | 0.61     |
| Post-plating   | Tin solder       | Bismuth (Bi)                                  | 7440-69-9  | 0         | 0.0                     | 0        |
|                | Tin solder       | Tin (Sn)                                      | 7440-31-5  | 1.61806   | 99.99                   | 3.67963  |
|                | Tin solder       | Copper (Cu)                                   | 7440-50-8  | 0         | 0.0                     | 0        |
|                | Tin solder       | Lead (Pb)                                     | 7439-92-1  | 0.00016   | 0.01                    | 0.00037  |
|                | Tin solder       | Antimony (Sb)                                 | 7440-36-0  | 0         | 0.0                     | 0        |
| Subtotal       |                  |                                               |            | 1.61822   | 100                     | 3.68     |
| Lead Frame     | Copper alloy     | Misc. Phosphor compounds (generic)            | 7723-14-0  | 0.00789   | 0.02                    | 0.01794  |
|                | Copper alloy     | Iron (Fe)                                     | 7439-89-6  | 0.03156   | 0.08                    | 0.07178  |
|                | Copper alloy     | Copper (Cu)                                   | 7440-50-8  | 39.33461  | 99.7                    | 89.45084 |
|                | Pure metal layer | Silver (Ag)                                   | 7440-22-4  | 0.07891   | 0.2                     | 0.17944  |
| Subtotal       |                  |                                               |            | 39.45297  | 100                     | 89.72    |
| Adhesive       | Polymer          | Paraffin wax                                  | 8002-74-2  | 0.21987   | 20.0                    | 0.5      |
|                | Polymer          | Epoxy resin system                            |            | 0.08795   | 8.0                     | 0.2      |
|                | Filler           | Silver (Ag)                                   | 7440-22-4  | 0.79152   | 72.0                    | 1.8      |
| Subtotal       |                  |                                               |            | 1.09934   | 100                     | 2.5      |
| Mould Compound | Polymer          | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8 | 1.4387    | 2.5                     | 3.27175  |
|                | Polymer          | Phenol Formaldehyde resin (generic)           | 9003-35-4  | 4.3161    | 7.5                     | 9.81525  |
|                | Filler           | Silica -amorphous-                            | 7631-86-9  | 21.29278  | 37.0                    | 48.4219  |
|                | Pigment          | Carbon black                                  | 1333-86-4  | 0.28774   | 0.5                     | 0.65435  |
|                | Polymer          | Epoxy resin system                            |            | 8.63221   | 15.0                    | 19.6305  |
|                | Filler           | Silicon Dioxide (SiO2)                        | 14808-60-7 | 21.29278  | 37.0                    | 48.4219  |
|                | Flame retardant  | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4  | 0.28774   | 0.5                     | 0.65435  |
| Subtotal       |                  |                                               |            | 57.54805  | 100                     | 130.87   |
| Wire           | Pure metal       | Copper (Cu)                                   | 7440-50-8  | 0.01319   | 100.0                   | 0.03     |
|                | Subtotal         |                                               |            | 0.01319   | 100                     | 0.03     |
| Total          |                  |                                               |            | 100.00001 | 100                     | 227.41   |

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